

REMARKS

The present application was filed on February 26, 2004 with claims 1 through 20. Claims 1 through 20 are presently pending in the above-identified patent application.

In the Office Action, the Examiner rejected claims 1-20 under 35 U.S.C. §102(b) as being anticipated by Giles et al. (United States Publication No. 2002/0118517).

Independent Claims 1, 8 and 14

Independent claim 1, 8 and 14 were rejected under 35 U.S.C. §102(b) as being anticipated by Giles et al. Regarding claim 1, for example, the Examiner asserts that Giles et al. discloses a modem module (par. 0041) for connecting to a carrier assembly, comprising:
10 circuitry (pars. 0027, 0042, PCB 200 includes circuitry 202) for interfacing with a telephone line (par. 0014); and one or more solder pads (FIG. 2A, 206) for connecting a signal line of said modem module (par. 0014) to said carrier assembly (FIG. 2A, 200).

In one aspect of the present invention, a modem module is provided that may be attached to a motherboard and thereby eliminates the need to recertify the motherboard.
15 Applicants note that the Examiner does not allege that Giles et al. discloses solder pads *on the modem module*, as variously required by each independent claim. The Examiner references the solder pads 206 in FIG. 2A, *but these solder pads are on the PCB* (i.e., the “carrier assembly,” using the terminology of the current claims).

As discussed in par. 0043, and shown in FIG. 2A, chip component assembly 300
20 (which is analogous to the claimed modem module) “includes a plurality of *chip components 302* arranged so that each contacts a respective solder pad 206.” (emphasis added). The chip components 302 are **not** solder pads.

In addition, the solder pads 206 of Giles do not connect a *signal line of the
modem module* to the carrier assembly, as further variously required by each independent claim.
25 Again, rather, the solder pads 206 connect the “*chip components 302*” to the PCB. The solder pads 206 are “in communication with electronic circuitry of the printed circuit board.” See, Abstract.

Thus, Giles et al. do *not* disclose or suggest one or more solder pads for
connecting a *signal line of a modem module to a carrier assembly*. Independent claims 1, 8, and
30 14 require one or more solder pads for connecting a *signal line of said modem module* to said carrier assembly.

Applicants respectfully request withdrawal of the rejection of independent claims 1, 8 and 14.

Dependent Claims 2-7, 9-13 and 15-20

Claims 2-7, 9-13, and 15-20 are dependent on claims 1, 8, and 14, respectively, and are therefore patentably distinguished over Giles et al. because of their dependency from amended independent claims 1, 8, and 14 for the reasons set forth above, as well as other elements these claims add in combination to their base claim.

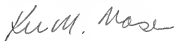
Conclusion

All of the pending claims following entry of the amendments, i.e., claims 1-20, are in condition for allowance and such favorable action is earnestly solicited.

If any outstanding issues remain, or if the Examiner has any further suggestions for expediting allowance of this application, the Examiner is invited to contact the undersigned at the telephone number indicated below.

The Examiner's attention to this matter is appreciated.

Respectfully submitted,



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